IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Currently Amended): An eddy-current sensor for nondestructive testing, comprising:

a planar exciting coil of meander-type at least having a pair of current lines in parallel with each other through which exciting currents flow in opposite directions to each other during the testing, for generating an alternative magnetic field applied to a subject to be nondestructively tested by said exciting currents, and

at least one spin-valve magnetoresistive element comprising a multilayered film laminated in parallel with a planar plane of said exciting coil, and positioned on a central axis between said pair of current lines and on the opposite side to said subject in relation to said exciting coil, for detecting a magnetic field generated ~~newly~~ from said subject by an eddy-current induced by said alternative magnetic field,

said multilayered film including a free-magnetization-direction layer magnetized perpendicularly to said pair of current lines under a condition without any external magnetic field and a pinned-magnetization-direction layer magnetized in parallel with said pair of current lines.

Claims 2-6 (Cancelled).

Claim 7 (Currently Amended): The sensor as claimed in claim 1, wherein said at least one spin-valve magnetoresistive element is a single spin-valve magnetoresistive element positioned on a central axis between said pair of current lines.

Claim 8 (Currently Amended): The sensor as claimed in claim 1, wherein said at least one spin-valve magnetoresistive element is a plurality of spin-valve magnetoresistive elements aligned on a central axis between said pair of current lines.

Claim 9 (Currently Amended): The sensor as claimed in claim 1, wherein said at least one spin-valve magnetoresistive element is a single spin-valve magnetoresistive element, and the sensor comprises at least one thin-film chip comprising ~~comprises~~ a chip substrate, said single spin-valve magnetoresistive element ~~a plurality of magnetoresistors~~ formed on said chip substrate, and ~~at least one thin-film chip each of which has a plurality of pairs~~ a pair of electrode terminals connected ~~respectively~~ to both ends of said single spin-valve magnetoresistive element ~~a plurality of magnetoresistors~~, and said at least one thin-film chip is bonded on said exciting coil.

Claim 10 (Original): The sensor as claimed in claim 9, wherein said at least one thin-film chip is a single thin-film chip, positioned on a central axis between said pair of current lines and bonded on said exciting coil.

Claim 11 (Original): The sensor as claimed in claim 9, wherein said at least one thin film chip is a plurality of thin-film chips, aligned on a central axis between said pair of current lines and bonded on said exciting coil.

Claim 12 (Currently Amended): The sensor as claimed in claim 1, wherein said ~~exciting coil is a meander-type coil~~ at least one spin-valve magnetoresistive element is a plurality of spin-valve magnetoresistive elements, and the sensor comprises at least one thin-film chip comprising a chip substrate, said plurality of spin-valve magnetoresistive elements

formed on said chip substrate, and a plurality of pairs of electrode terminals connected respectively to both ends of said plurality of spin-valve magnetoresistive elements, and said at least one thin-film chip is bonded on said exciting coil.

Claim 13 (Currently Amended): The sensor as claimed in claim ~~1~~ 12, wherein said exciting coil comprises a coil conductor layer formed on a substrate and an insulating layer covering said coil conductor layer.

Claim 14 (New): The sensor as claimed in claim 12, wherein said at least one thin-film chip is a single thin-film chip, positioned on a central axis between said pair of current lines and bonded on said exciting coil.

Claim 15 (New): The sensor as claimed in claim 12, wherein said at least one thin film chip is a plurality of thin-film chips, aligned on a central axis between said pair of current lines and bonded on said exciting coil.